

IN THE SPECIFICATION:

Page 1, between lines 5 and 6, please insert:

--This is a continuation-in-part of Application No. 09/516,652 filed March 1, 2000.--

AC
10/31/01
6,586,836
A now pending

IN THE CLAIMS:

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- 1 ~~10.~~ A method of fabricating microelectronic dice, comprising:
 - 2 providing a first encapsulated die assembly having an active surface and a back
 - 3 surface, said first encapsulated die assembly including at least one first microelectronic
 - 4 die having an active surface and at least one side and a first packaging material adjacent
 - 5 said at least one first microelectronic die side, wherein said first packaging material
 - 6 comprises a first microelectronic package core and a first encapsulation material, and
 - 7 wherein said first encapsulation material comprises at least a portion of said first
 - 8 encapsulation die assembly back surface;
 - 9 providing a second encapsulated die assembly having an active surface and a back
 - 10 surface, said second encapsulated die assembly including at least one second
 - 11 microelectronic die having an active surface and at least one side and a second packaging
 - 12 material adjacent said at least one second microelectronic die side; and
 - 13 attaching said first encapsulated die assembly back surface to said second
 - 14 encapsulated assembly back surface.

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1 ~~12~~ 21. The method of claim ~~10~~, wherein said providing a first encapsulated die
2 assembly comprises:
3 providing at least one first microelectronic die having an active surface
4 and at least one side;
5 abutting a protective film against said at least one first microelectronic die
6 active surface;
7 abutting said first microelectronic package core against said protective
8 film;
9 encapsulating said at least one microelectronic die with an encapsulation
10 material adjacent said at least one first microelectronic die side, wherein said
11 encapsulation material provides at least one surface of said encapsulation material
12 substantially planar to said first microelectronic die active surface; and
13 removing said protective film.

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1 ~~14~~ 23. A method of fabricating a microelectronic package, comprising:
2 forming a first encapsulated die assembly comprising:
3 providing at least one first microelectronic die having an active
4 surface and at least one side;
5 abutting a protective film against said at least one first
6 microelectronic die active surface;
7 abutting a first microelectronic package core against said protective
8 film; and

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9 encapsulating said at least one microelectronic die with an
10 packaging material adjacent said at least one first microelectronic die side
11 to form a first encapsulated die active surface and a first encapsulated die
12 back surface;
13 forming a second encapsulated die assembly comprising:
14 providing at least one second microelectronic die having an active
15 surface and at least one side;
16 abutting a protective film against said at least one second
17 microelectronic die active surface; and
18 encapsulating said at least one microelectronic die with an
19 packaging material adjacent said at least one second microelectronic die
20 side to form a second encapsulated die active surface and a second
21 encapsulated die back surface; and
22 attaching said first encapsulated die assembly back surface to said second
23 encapsulated assembly back surface.
